

Features

- I_o 0.5A
- V_{RRM} 200V~800V
- Glass passivated chip
- High surge forward current capability
- Supersmall size
- Component in accordance to ROHS 2002/95/EC and WEEE2002/96/WC
- Halogen Free product

Mechanical data

Case: ZB(DIP)

Epoxy meets UL 94V-0 flammability rating

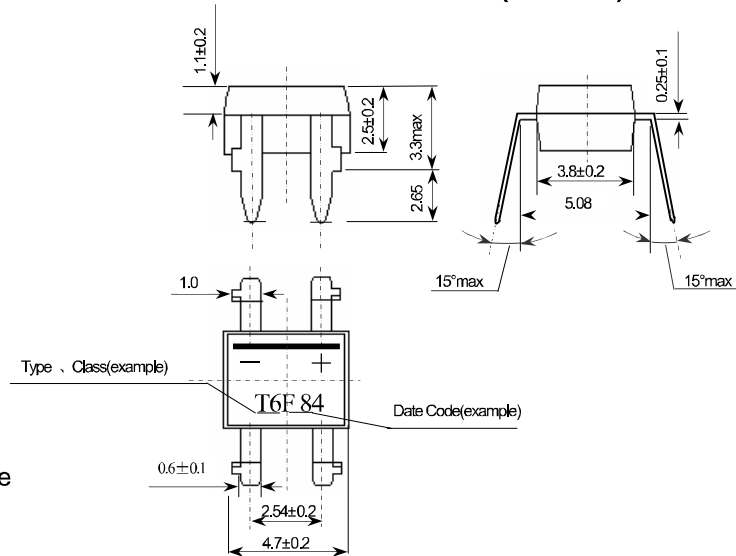
Terminals: Pure tin plated leads, solderable per J-STD-002 and JESD22-B102, E3

suffix for consumer grade, meet JESD201

class 1A whisker test.

Polarity: As marked on body

Outline Dimensions and Mark(Unit: mm)



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	T1ZB20F	T1ZB40F	T1ZB60F	T1ZB80F
Storage Temperature	T_{stg}	°C		-40 ~ +150			
Junction Temperature	T_j	°C		+150			
Repetitive Peak Reverse Voltage	V_{RRM}	V		200	400	600	800
Average Rectified Output Current	I_o	A	50Hz sine wave, R-load, $T_a=25^{\circ}\text{C}$	0.5			
Surge(Non-repetitive)Forward Current	I_{FSM}	A	50Hz sine wave, 1 cycle, $T_a=25^{\circ}\text{C}$	30			

Electrical Characteristics ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_F=0.4A$, Pulse measurement, Rating of per diode	1.05
Peak Reverse Current	I_{RRM1}	μA	$V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	10
Thermal Resistance	$R_{\theta J-A}$	°C/W	Between junction and ambient, On glass-epoxy substrate	134
	$R_{\theta J-L}$		Between junction and lead	20

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25^\circ\text{C}$ unless otherwise noted)

